

Amendments to the Claims:

This listing of claims will replace all prior versions, and listing, of claims in the present application:

Listing of Claims:

1. (currently amended) An integrated circuit system comprising:
at least one integrated circuit having a substrate with at least one semiconductor component assembled on the substrate the substrate being a direct copper bonding substrate which is formed by a ceramic structure coated at least partially with copper on the front and rear side thereof;
a cooling body configured to dissipate heat generated by the integrated circuit; and
a latent heat storage module having a latent heat storage medium which is thermally connected to the cooling body to temporarily store the heat generated by the integrated circuit and to convey it to the cooling body, the substrate being in direct thermal contact with the latent heat storage module.
2. (canceled)
3. (canceled)
4. (original) An integrated circuit system according to claim 1, wherein the substrate is mechanically fixed to the latent heat storage module by a material-joining connection.
5. (original) An integrated circuit system according to claim 4, wherein the material-joining connection is formed by soldering, welding or gluing.
6. (original) An integrated circuit system according to claim 1, wherein the latent heat storage module has a latent heat storage housing which forms a hollow body filled with the latent heat storage medium.

7-11 (canceled)

12. (original) An integrated circuit system according to claim 1, wherein the latent heat storage housing includes a wall in thermal contact with the cooling body and at least partially formed by the cooling body.

13-16 (canceled)

17. (original) An integrated circuit system according to claim 1, wherein the semiconductor component is connected to the substrate by a soldered connection.

18. (original) An integrated circuit system according to claim 1, wherein the semiconductor component is connected to the substrate by a glued connection.

19. (canceled)

20. (original) An integrated circuit system according to claim 1, wherein the latent heat storage medium is paraffin.

21-23 (canceled)

24. (original) An integrated circuit system according to claim 1, wherein the cooling body has at least one cooling rib for conveyance of heat.

25. (original) An integrated circuit system according to claim 1, wherein the cooling body is connectable to a cooling circuit.

26 - 38 (canceled)